



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20141121003

**Qualification of New Mold Compound for selected Devices in the PDIP package
Change Notification / Sample Request**

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

PCN# 20141121003
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20141121003			PCN Date:	12/04/2014						
Title:	Qualification of New Mold Compound for selected Devices in the PDIP package										
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services						
Proposed 1st Ship Date:	3/04/2015	Estimated Sample Availability:		Date provided upon request							
Change Type:											
☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials						
☐	Design	☐	Electrical Specification	☐	Mechanical Specification						
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process						
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process						
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process						
	☐	Part number change									
PCN Details											
Description of Change:											
Texas Instruments is pleased to announce the qualification of a new mold compound for the list of selected PDIP packaged devices shown below.											
<table border="1"> <thead> <tr> <th>What</th> <th>Current</th> <th>New</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#101331374 or SID#8000779</td> <td>SID#101375725</td> </tr> </tbody> </table>		What	Current	New	Mold Compound	SID#101331374 or SID#8000779	SID#101375725				
What	Current	New									
Mold Compound	SID#101331374 or SID#8000779	SID#101375725									
Reason for Change:											
Material Standardization											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):											
None											

Changes to product identification resulting from this PCN:
None

Product Affected				
ADC0831CCN	LF412ACN	LM2904N/NOPB	LM4562NA/NOPB	
ADC0832CCN	LF412CN	LM2904N/SL161612	LM6134BIN	
COP431CN	LF442CN/NOPB	LM2907N-8/NOPB	LM6134BIN/NOPB	
COP432CN	LF444CN/NOPB	LM2917N-8/NOPB	LM78S40N	
DAC0808LCN/SL107322	LM10CN/NOPB	LM2917N/NOPB	LM833N/NOPB	
DS14C88N/NOPB	LM13700N	LM311N	LMC6042AIN	
DS26LS32ACN	LM231N/NOPB	LM311N/NOPB	LMC6042IN/NOPB	
DS26LS32ACN/NOPB	LM2574N-12	LM319N	LMC6044IN	
DS3668N	LM2574N-ADJ	LM324AN/NOPB	LMC6044IN/NOPB	
DS3668N/HAPB	LM2594N-12/NOPB	LM324AN/PB	LMC6064IN	
DS3695N	LM2594N-3.3/NOPB	LM324N/NOPB	LMC6462AIN	
DS3695TN	LM2597N-5.0/NOPB	LM339N/NOPB	LMC6462AIN/NOPB	
DS75176BN	LM2671N-5.0	LM348N/NOPB	LMC6464BIN	
DS8921N/NOPB	LM2671N-ADJ/NOPB	LM3524DN	LMC6482AIN	

DS8923AN	LM2672N-12/NOPB	LM3524DN/NOPB	LMC6482AIN/NOPB
DS8923AN/NOPB	LM2672N-ADJ/NOPB	LM358N	LMC6484AIN/NOPB
DS96175CN	LM2674N-12/NOPB	LM358N/NOPB	LMC660CN
DS96176CN	LM2674N-5.0/NOPB	LM361N/NOPB	LMC7660IN/NOPB
LF353N	LM2675N-12/NOPB	LM386N-1/NOPB	LME49720NA/NOPB
LF356N/NOPB	LM2675N-5.0/NOPB	LM386N-3	LME49860NA/NOPB
LF398N	LM2901N/NOPB	LM386N-3/NOPB	MLM311P
LF398N/NOPB	LM2901N/SL65262	LM386N-4/NOPB	TL072
LF411ACN/NOPB	LM2903N/NOPB	LM393N/NOPB	TP3054N
LF411CN/NOPB			

Qualification Report

PDIP mold compound SID#8000779 discontinuance in AP1
Approved 06/10/2014

Product Attributes

Attributes	Qual Device: LF444CN/NOPB	Qual Device: LM319N
Assembly Site	AP1	AP1
Package Family	PDIP	PDIP
Wafer Fab Supplier	GL	GL
Wafer Fab Process	BPBIFET.13.1	BPSLM.8.1

- QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LF444CN/NOPB	Qual Device: LM319N
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	3/140/0
AC	Autoclave 121C	96 Hours	3/240/0	-
UHA	Unbiased HAST 130C/85%RH	96 Hours	3/240/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/240/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/240/0	-

-- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20130502-84221

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com